

**Amendments to the Specification**

Please replace the paragraph beginning at page 10, line 10 with the following rewritten paragraph:

--In order to further reduce the unwanted thermal expansion of the magnetic head 142, a heat transfer layer 146 may additionally be fabricated within the head. the protrusion in a magnetic head that uses only negative thermal expansion materials without the use of the heat transfer layer 142, because the temperature buildup within the head is reduced by the heat transfer layer. Such heat transfer layers are described in detail in U.S. Patent Application Serial No. 10/215,230, ~~Docket No. SJO9-2002-0037US1~~, entitled "Heat Sink for a Magnetic Recording Head," by Savas Gider et al, which is assigned to the assignee of this application and incorporated herein as though set forth in full. The incorporated patent application discloses heat transfer layers, heat sinks and the like, any or all of which may be incorporated into various embodiments of the invention.--